

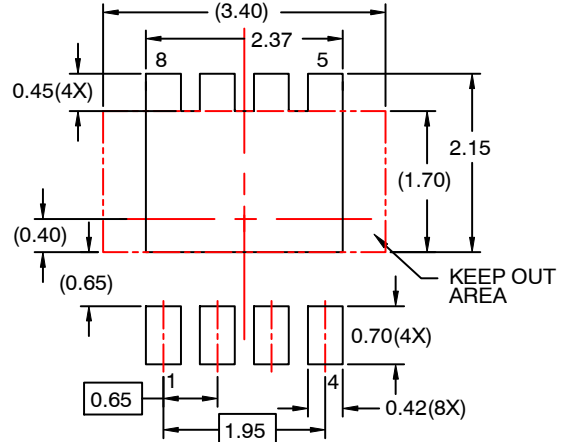
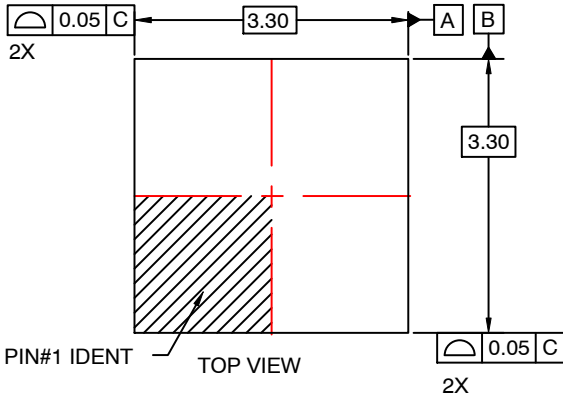
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



WDFN8 3.3x3.3, 0.65P
CASE 511DH
ISSUE O

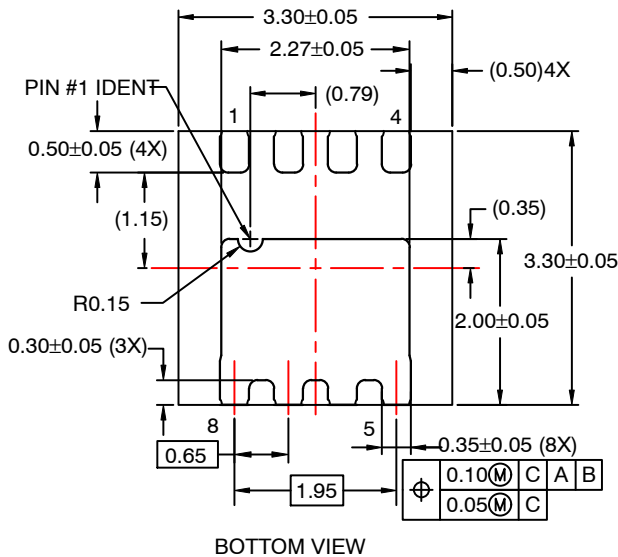
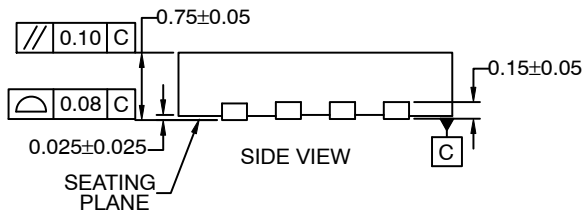
DATE 31 JUL 2016



RECOMMENDED LAND PATTERN

NOTES:

- A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.



BOTTOM VIEW

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